

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A method for manufacturing an insulating resin layer, comprising:
 - forming a photosensitive resin layer on a substrate;
 - a first exposure step of performing exposure for the photosensitive resin layer;
 - developing the photosensitive resin layer subjected to the exposure; and
 - a second exposure step of performing exposure for the developed photosensitive resin layer at a substrate temperature of 100 to 250°C with an illuminance of 80 mW/cm² or more and an irradiation energy of ~~5 to 30 J/cm²~~; greater than 10 J/cm² to less than or equal to 30 J/cm².
2. (Previously Presented) The method for manufacturing an insulating resin layer according to Claim 1, the photosensitive resin layer containing an acrylic resin as a main component.
3. (Previously Presented) The method for manufacturing an insulating resin layer according to Claim 1, the second exposure step being performed using a high-pressure mercury lamp having a luminescence peak at a wavelength of about 365 nm, and the illuminance on the substrate being 80 mW/cm² or more at a wavelength of 350 to 380 nm.
4. (Previously Presented) The method for manufacturing an insulating resin layer according to Claim 3, the second exposure step being performed using a filter that removes rays having a wavelength of less than 300 nm from rays that are emitted from the high-pressure mercury lamp.

5. (Previously Presented) A substrate for electro-optical devices, comprising an insulating resin layer obtained by the insulating resin layer-manufacturing method according to Claim 1.

6. (Previously Presented) The substrate for electro-optical devices according to Claim 5, the insulating resin layer having a transmittance of 95% or more with respect to a colored ray having a wavelength of 400 nm.

7. (Previously Presented) The substrate for electro-optical devices according to Claim 5, the insulating resin layer having a thickness of 3 μm or more.

8. (Previously Presented) A method for manufacturing an electro-optical device, comprising a step of manufacturing an insulating resin layer according to Claim 1.

9. (Previously Presented) An electro-optical device comprising an insulating resin layer formed by a manufacturing method according to Claim 1.

10. (Previously Presented) A method for manufacturing an electro-optical device, comprising a step of using a substrate for electro-optical devices according to Claim 5.

11. (Previously Presented) An electro-optical device comprising a substrate for electro-optical devices according to Claim 5.